

ABSTRACT

The present invention creates a shielding device for a chuck, a corresponding chuck and a corresponding wafer prober setup. The shielding device is fitted with a ring mechanism (30) having a first ring (30a) and a second ring (30b); wherein the first ring (30a) can be attached to an outer periphery (PP) of the chuck (CH) of the wafer prober (1) and the second ring (30b) is mounted on the first ring (30a) so as to be displaceable along a vertical axis (HA) of the chuck (CH) in relation to the first ring (30a) and a pretensioning device (FE) for the elastic pretensioning of the second ring (30b) in relation to the first ring (30a) along the vertical axis (HA) of the chuck (CH), so that the second ring (30b) in the chuck (CH) projects beyond the upper side (OS) of the chuck (CH) in the mounted state. The second ring (30b) has a cavity (H) and bores (B) communicating therewith, wherein the cavity (H) has a connection (A) for connecting a gas supply device (LV). By means of the gas supply device (LV), an air bearing (LL) can be produced via the bores (B) opposite a plate-shaped counter bearing (20; 11b) above the second ring (30b) in relation to the vertical axis (HA) of the chuck (CH), wherein the pretensioning device (FE) can be compressed by the air bearing (LL) in such a manner that there is no contact between the second ring (30b) and the plate-shaped counter bearing (20; 11b).

(Fig. 1)